CNational Semiconduc
100351
Low Power Hex D Flip-Flop

## General Description

The 100351 contains six D-type edge-triggered, master/ slave flip-flops with true and complement outputs, a pair of common Clock inputs ( $\mathrm{CP}_{\mathrm{a}}$ and $\mathrm{CP}_{\mathrm{b}}$ ) and common Master Reset (MR) input. Data enters a master when both $\mathrm{CP}_{\mathrm{a}}$ and $\mathrm{CP}_{\mathrm{b}}$ are LOW and transfers to the slave when $\mathrm{CP}_{\mathrm{a}}$ and $\mathrm{CP}_{\mathrm{b}}$ (or both) go HIGH. The MR input overrides all other inputs and makes the Q outputs LOW. All inputs have $50 \mathrm{k} \Omega$ pull-down resistors.

## Features

- $40 \%$ power reduction of the 100151
- 2000V ESD protection
- Pin/function compatible with 100151
- Voltage compensated operating range: -4.2 V to -5.7 V
- Standard Microcircuit Drawing (SMD) 5962-9457901

Logic Symbol


## Connection Diagrams



## Logic Diagram

Truth Tables (Each Flip-flop)
Synchronous Operation

| Inputs |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| $\mathbf{D}_{\mathbf{n}}$ | $\mathbf{C P}_{\mathbf{a}}$ | $\mathbf{C P}_{\mathbf{b}}$ | $\mathbf{M R}$ | $\mathbf{Q}_{\mathbf{n}}(\mathrm{t}+\mathbf{1})$ |
| L | $\sim$ | L | L | L |
| H | - | L | L | H |
| L | L | $\sim$ | L | L |
| H | L | - | L | H |
| X | H | - | L | $\mathrm{Q}_{\mathrm{n}}(\mathrm{t})$ |
| X | $\sim$ | H | L | $\mathrm{Q}_{\mathbf{n}}(\mathrm{t})$ |
| X | L | L | L | $\mathrm{Q}_{\mathrm{n}}(\mathrm{t})$ |




Asynchronous Operation

| Inputs |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| Outputs |  |  |  |  |
| $\mathbf{D}_{\mathbf{n}}$ | $\mathbf{C P}_{\mathbf{a}}$ | $\mathbf{C P}_{\mathbf{b}}$ | $\mathbf{M R}$ | $\mathbf{Q}_{\mathbf{n}}(\mathbf{t + 1})$ |
| X | X | X | H | L |

H = HIGH Voltage Leve
L = LOW Voltage Level
X = Don't Care
$t=$ Time before CP positive transition
$t+1=$ Time after CP positive transition
$\sim=$ LOW-to-HIGH transition

Absolute Maximum Ratings (Note 1)
If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.
Above which the useful life may be impaired
Storage Temperature ( $\mathrm{T}_{\mathrm{STG}}$ )
$-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Maximum Junction Temperature ( $\mathrm{T}_{\mathrm{J}}$ )
Ceramic
$+175^{\circ} \mathrm{C}$
$\mathrm{V}_{\mathrm{EE}}$ Pin Potential to Ground Pin
Input Voltage (DC)

$$
-7.0 \mathrm{~V} \text { to }+0.5 \mathrm{~V}
$$

$$
V_{E E} \text { to }+0.5 \mathrm{~V}
$$

Output Current (DC Output HIGH)
$-50 \mathrm{~mA}$

## Recommended Operating Conditions

Case Temperature ( $\mathrm{T}_{\mathrm{C}}$ )
Military
$-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$
Supply Voltage ( $\mathrm{V}_{\mathrm{EE}}$ )
-5.7 V to -4.2 V
Note 1: Absolute maximum ratings are those values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.
Note 2: ESD testing conforms to MIL-STD-883, Method 3015.

## Military Version

## DC Electrical Characteristics

$\mathrm{V}_{\mathrm{EE}}=-4.2 \mathrm{~V}$ to $-5.7 \mathrm{~V}, \mathrm{~V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCA}}=\mathrm{GND}, \mathrm{T}_{\mathrm{C}}=-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$

| Symbol | Parameter | Min | Max | Units | $\mathrm{T}_{\mathrm{c}}$ | Conditions |  | Notes |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{OH}}$ | Output HIGH Voltage | -1025 | -870 | mV | $\begin{gathered} 0^{\circ} \mathrm{C} \text { to } \\ +125^{\circ} \mathrm{C} \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\text {IN }}=\mathrm{V}_{\mathrm{IH}}(\operatorname{Max}) \\ \text { or } \mathrm{V}_{\mathrm{IL}}(\operatorname{Min}) \end{gathered}$ | Loading with $50 \Omega$ to -2.0 V | (Notes 3, 4, 5) |
|  |  | -1085 | -870 | mV | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{V}_{\mathrm{OL}}$ | Output LOW Voltage | -1830 | -1620 | mV | $\begin{gathered} 0^{\circ} \mathrm{C} \text { to } \\ +125^{\circ} \mathrm{C} \end{gathered}$ |  |  |  |
|  |  | -1830 | -1555 | mV | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{V}_{\text {OHC }}$ | Output HIGH Voltage | -1035 |  | mV | $\begin{gathered} 0^{\circ} \mathrm{C} \text { to } \\ +125^{\circ} \mathrm{C} \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\text {IN }}=V_{\text {IH }}(\operatorname{Min}) \\ \text { or } V_{\text {IL }}(\operatorname{Max}) \end{gathered}$ | Loading with $50 \Omega$ to -2.0 V | (Notes 3, 4, 5) |
|  |  | -1085 |  | mV | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{V}_{\text {OLC }}$ | Output LOW Voltage |  | -1610 | mV | $\begin{gathered} 0^{\circ} \mathrm{C} \text { to } \\ +125^{\circ} \mathrm{C} \end{gathered}$ |  |  |  |
|  |  |  | -1555 | mV | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\overline{\mathrm{V}_{\mathrm{IH}}}$ | Input HIGH Voltage | -1165 | -870 | mV | $\begin{gathered} -55^{\circ} \mathrm{C} \text { to } \\ +125^{\circ} \mathrm{C} \end{gathered}$ | Guaranteed HIGH Signal for All Inputs |  | (Notes 3, 4, 5, 6) |
| $\overline{\mathrm{V} \text { IL }}$ | Input LOW Voltage | -1830 | -1475 | mV | $\begin{gathered} -55^{\circ} \mathrm{C} \text { to } \\ +125^{\circ} \mathrm{C} \end{gathered}$ | Guaranteed LOW Signal for All Inputs |  | (Notes 3, 4, 5, 6) |
| $\mathrm{I}_{\text {IL }}$ | Input LOW Current | 0.50 |  | $\mu \mathrm{A}$ | $\begin{aligned} & \hline-55^{\circ} \mathrm{C} \text { to } \\ & +125^{\circ} \mathrm{C} \\ & \hline \end{aligned}$ | $\begin{aligned} & \hline \mathrm{V}_{\mathrm{EE}}=-4.2 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{IL}}(\mathrm{Min}) \\ & \hline \end{aligned}$ |  | (Notes 3, 4, 5) |
| $\overline{I_{\mathrm{IH}}}$ | $\begin{aligned} & \text { Input HIGH Current } \\ & \qquad \begin{array}{r} \text { CP, MR } \\ D_{0}-D_{5} \\ \hline \end{array} \\ & \hline \end{aligned}$ |  | $\begin{aligned} & 350 \\ & 240 \\ & \hline \end{aligned}$ | $\mu \mathrm{A}$ | $\begin{gathered} 0^{\circ} \mathrm{C} \text { to } \\ +125^{\circ} \mathrm{C} \end{gathered}$ | $\begin{aligned} & \mathrm{V}_{\mathrm{EE}}=-5.7 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{IH}}(\mathrm{Max}) \end{aligned}$ |  | (Notes 3, 4, 5) |
|  | $\begin{array}{r} \mathrm{CP}, \mathrm{MR} \\ \mathrm{D}_{0}-\mathrm{D}_{5} \\ \hline \end{array}$ |  | $\begin{aligned} & \hline 500 \\ & 340 \\ & \hline \end{aligned}$ | $\mu \mathrm{A}$ | $-55^{\circ} \mathrm{C}$ |  |  |  |  |
| $\mathrm{l}_{\mathrm{EE}}$ | Power Supply Current | -135 | -50 | mA | $\begin{gathered} -55^{\circ} \mathrm{C} \text { to } \\ +125^{\circ} \mathrm{C} \end{gathered}$ | Inputs Open |  | (Notes 3, 4, 5) |

Note 3: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals $-55^{\circ} \mathrm{C}$ ), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.
Note 4: Screen tested $100 \%$ on each device at $-55^{\circ} \mathrm{C},+25^{\circ} \mathrm{C}$, and $+125^{\circ} \mathrm{C}$, Subgroups $1,2,3,7$, and 8 .
Note 5: Sample tested (Method 5005, Table I) on each manufactured lot at $-55^{\circ} \mathrm{C},+25^{\circ} \mathrm{C}$, and $+125^{\circ} \mathrm{C}$, Subgroups A1, 2, 3, 7 , and 8 .
Note 6: Guaranteed by applying specified input condition and testing $\mathrm{V}_{\mathrm{OH}} / \mathrm{V}_{\mathrm{OL}}$.

## AC Electrical Characteristics

| Symbol | Parameter | $\mathrm{T}_{\mathrm{C}}=-55^{\circ} \mathrm{C}$ |  | $\mathrm{T}_{\mathrm{C}}=+25^{\circ} \mathrm{C}$ |  | $\mathrm{T}_{\mathrm{C}}=+125^{\circ} \mathrm{C}$ |  | Units | Conditions | Notes |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Max | Min | Max | Min | Max |  |  |  |
| $\mathrm{f}_{\text {max }}$ | Toggle Frequency | 375 |  | 375 |  | 375 |  | MHz | Figures 2, 3 | (Note 10) |
| $\begin{aligned} & \mathrm{t}_{\mathrm{PLH}} \\ & \mathrm{t}_{\mathrm{PHL}} \end{aligned}$ | Propagation Delay $\mathrm{CP}_{\mathrm{a}}, \mathrm{CP}_{\mathrm{b}}$ to Output | 0.40 | 2.40 | 0.50 | 2.20 | 0.50 | 2.60 | ns | Figures 1, 3 | (Notes 7, 8, 9) |
| $\begin{aligned} & \hline \mathrm{t}_{\mathrm{PLH}} \\ & \mathrm{t}_{\mathrm{PHL}} \end{aligned}$ | Propagation Delay MR to Output | 0.60 | 2.70 | 0.70 | 2.60 | 0.80 | 2.90 | ns | Figures 1, 4 |  |
| $\begin{aligned} & \mathrm{t}_{\mathrm{TLH}} \\ & \mathrm{t}_{\mathrm{THL}} \\ & \hline \end{aligned}$ | Transition Time $20 \%$ to $80 \%, 80 \%$ to $20 \%$ | 0.20 | 1.60 | 0.20 | 1.60 | 0.20 | 1.60 | ns | Figures 1, 3 | (Note 10) |
| $\mathrm{t}_{\mathrm{s}}$ | Setup Time $D_{0}-D_{5}$ <br> MR (Release Time) | $\begin{aligned} & 0.90 \\ & 1.60 \end{aligned}$ |  | $\begin{aligned} & 0.80 \\ & 1.80 \end{aligned}$ |  | $\begin{aligned} & 0.90 \\ & 2.60 \\ & \hline \end{aligned}$ |  | ns | Figure 5 <br> Figure 4 |  |
| $\mathrm{t}_{\mathrm{h}}$ | Hold Time $\mathrm{D}_{0}-\mathrm{D}_{5}$ | 1.50 |  | 1.40 |  | 1.60 |  | ns | Figure 5 |  |
| $\overline{t_{p w}(H)}$ | Pulse Width HIGH $\mathrm{CP}_{\mathrm{a}}, \mathrm{CP}_{\mathrm{b}}$, MR | 2.00 |  | 2.00 |  | 2.00 |  | ns | Figures 3, 4 |  |

Note 7: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals $-55^{\circ} \mathrm{C}$ ), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures
Note 8: Screen tested $100 \%$ on each device at $+25^{\circ} \mathrm{C}$, Temperature only, Subgroup A9.
Note 9: Sample tested (Method 5005, Table I) on each Mfg. lot at $+25^{\circ} \mathrm{C}$, Subgroup A9, and at $+125^{\circ} \mathrm{C}$, and $-55^{\circ} \mathrm{C}$ Temperature, Subgroups A10 and A11.
Note 10: Not tested at $+25^{\circ} \mathrm{C},+125^{\circ} \mathrm{C}$ and $-55^{\circ} \mathrm{C}$ Temperature (design characterization data)

## Test Circuitry



## Notes:

$\mathrm{V}_{\mathrm{CC}}, \mathrm{V}_{\mathrm{CCA}}=+2 \mathrm{~V}, \mathrm{~V}_{\mathrm{EE}}=-2.5 \mathrm{~V}$
L 1 and $\mathrm{L} 2=$ equal length $50 \Omega$ impedance lines
$R_{T}=50 \Omega$ terminator internal to scope
Decoupling $0.1 \mu \mathrm{~F}$ from GND to $\mathrm{V}_{\mathrm{CC}}$ and $\mathrm{V}_{\mathrm{EE}}$
All unused outputs are loaded with $50 \Omega$ to GND
$C_{\mathrm{L}}=$ Fixture and stray capacitance $\leq 3 \mathrm{pF}$
FIGURE 1. AC Test Circuit

## Test Circuitry (Continued)



Notes:
$\mathrm{V}_{\mathrm{CC}}, \mathrm{V}_{\mathrm{CCA}}=+2 \mathrm{~V}, \mathrm{~V}_{\mathrm{EE}}=-2.5 \mathrm{~V}$
L 1 and $\mathrm{L} 2=$ equal length $50 \Omega$ impedance lines
$R_{T}=50 \Omega$ terminator internal to scope
Decoupling $0.1 \mu \mathrm{~F}$ from $G N D$ to $\mathrm{V}_{\mathrm{CC}}$ and $\mathrm{V}_{\mathrm{EE}}$
All unused outputs are loaded with $50 \Omega$ to GND
$C_{L}=$ Jig and stray capacitance $\leq 3 \mathrm{pF}$
FIGURE 2. Toggle Frequency Test Circuit

## Switching Waveforms



FIGURE 3. Propagation Delay (Clock) and Transition Times

## Switching Waveforms (Continued)



FIGURE 4. Propagation Delay (Reset)


Notes:
$t_{s}$ is the minimum time before the transition of the clock that information must be present at the data input.
$t_{h}$ is the minimum time after the transition of the clock that information must remain unchanged at the data input.
FIGURE 5. Setup and Hold Time

Physical Dimensions inches (millimeters) unless otherwise noted


24-Lead Ceramic Dual-In-Line Package (0.400" Wide) (D) NS Package Number J24E


W24B (REV D)

## 24-Lead Quad Cerpak (F) NS Package Number W24B



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## 100351

Low Power Hex D Flip-Flop

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## Datasheet

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| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | Type | \# pins |  | SPICE | IBIS |  | Quantity | \$US each |  |  |
| 5962-9457901MXA | Cerdip | 24 | Full production | N/A | N/A | 区 | 50+ | \$39.6000 | $\begin{array}{\|l\|} \hline \text { tube } \\ \text { of } \\ 15 \end{array}$ | $\begin{array}{\|c\|} \hline[\operatorname{logoc} \phi \mathrm{Z} \phi \mathrm{~S} \phi 4 \phi \mathrm{~A} \$ \mathrm{E} \\ \text { 100351DMQB /Q } \\ 5962-9457901 \mathrm{MXA} \\ \hline \end{array}$ |
| 5962-9457901MYA | Cerquad | 24 | Full production | N/A | N/A | ® | 50+ | \$41.2000 | $\left\|\begin{array}{\|c} \text { tube } \\ \text { of } \\ 14 \end{array}\right\|$ | $\begin{gathered} \hline \hline \text { logo }] \& \mathrm{Z} \phi \mathrm{~S} \phi 4 \phi \mathrm{~A} \\ \text { Q\$E } 100351 \\ \text { FMQB } 5962 \\ \text {-9457901 } \\ \text { MYA } \end{gathered}$ |
| 5962-9457901VXA | Cerdip | 24 | Full production | N/A | N/A | . | 50+ | \$265.0000 | tube <br> of <br> 15 | $\begin{array}{\|c\|} \hline[\operatorname{logog}] ¢ \mathrm{Z} \phi \mathrm{~S} \phi 4 \not \subset \mathrm{~A} \$ E \\ \text { 100351J-QMLV } \\ 5962-9457901 \mathrm{VXA} \end{array}$ |
| 100351W-QMLV | Cerquad | 24 | Full production | N/A | N/A | . | 50+ | \$265.0000 | $\left\lvert\, \begin{array}{\|l\|} \|c\| \\ \text { tube } \\ \text { of } \\ 14 \end{array}\right.$ | $\begin{gathered} \hline \hline[\operatorname{logo}] \phi \mathrm{Z} \phi \mathrm{~S} \phi 4 \notin \mathrm{~A} \\ 100351 \mathrm{~W}- \\ \text { QMLV } 5962 \\ \text {-9457901 } \\ \text { VYA \$E } \end{gathered}$ |
| 100351 MW8 | waf |  | Full production | N/A | N/A | . |  |  | N/A | - |

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